

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Osamu CHIKAGAWA et al.	International Application No.: PCT/JP2005/019286
Application No.: Currently unknown	
Filing or 371(c) Date: Concurrently herewith	International Filing Date: October 20, 2005
Title: MULTILAYER SUBSTRATE WITH BUILT-IN CHIP-TYPE ELECTRONIC COMPONENT AND METHOD FOR MANUFACTURING THE SAME	

**PRELIMINARY AMENDMENT**

Mail Stop PCT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Prior to examination on the merits of the above-identified patent application,  
Applicants respectfully request entry and consideration of the following Amendment:

- ☒ **Amendments to the Specification** begin on page 2 of this paper.
- ☐ **Amendments to the Drawings** begin on page      of this paper and include an attached replacement sheet.
- ☒ **Amendments to the Claims** are reflected in the listing of the claims which begins on page 5 of this paper.
- ☒ **Remarks/Arguments** begin on page 8 of this paper.

Please note, if a box is not checked, then no corresponding amendment is being made.